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(54) Title: ETCH-STOP RESINS

(57) Abstract: Silicone resins comprising 5 to 50 mole% of (PhSiO_{3-x/2}(OH)_x) units and 50 to 95 mole% (HSiO_{(3-x)/2}(OH)_x), where Ph is a phenyl group, x has a value of 0, 1 or 2 and wherein the cured silicone resin has a critical surface free energy of 30 dynes/cm or higher. These resins are useful as etch stop layers for organic dielectric materials having a critical surface free energy of 40 dynes/cm or higher.



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